



Material Content Data Sheet



Halogen-Free

Sales Product Name	AIDK12S65C5	Issued	13. May 2021
MA#	MA001891238		
Package	PG-TO263-2-1	Weight*	1466.94 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	siliconcarbide	409-21-2	0.945	0.06	0.06	644	644
leadframe	inorganic material	phosphorus	7723-14-0	0.225	0.02		154	
	non noble metal	iron	7439-89-6	0.751	0.05		512	
	non noble metal	copper	7440-50-8	749.949	51.12	51.19	511231	511897
wire	non noble metal	aluminium	7429-90-5	1.567	0.11	0.11	1068	1068
encapsulation	inorganic material	zincoxide	1314-13-2	5.565	0.38		3794	
	miscellaneous	miscellaneous	-	22.261	1.52		15175	
	plastics	epoxy resin	-	83.479	5.69		56907	
	inorganic material	silicondioxide	60676-86-0	445.220	30.35	37.94	303502	379378
leadfinish	non noble metal	tin	7440-31-5	11.700	0.80	0.80	7976	7976
plating	inorganic material	phosphorus	7723-14-0	0.007			5	
	non noble metal	nickel	7440-02-0	2.778	0.19	0.19	1893	1898
solder	non noble metal	tin	7440-31-5	0.016			11	
	noble metal	silver	7440-22-4	0.020			14	
	non noble metal	lead	7439-92-1	0.778	0.05	0.05	531	556
heatspreader	inorganic material	phosphorus	7723-14-0	0.043			29	
	non noble metal	iron	7439-89-6	0.142	0.01		97	
	non noble metal	copper	7440-50-8	141.498	9.65	9.66	96457	96583
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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